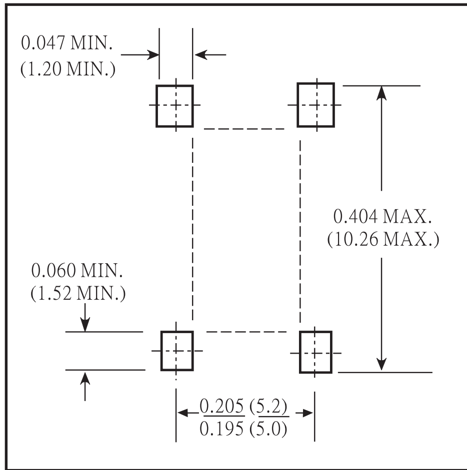
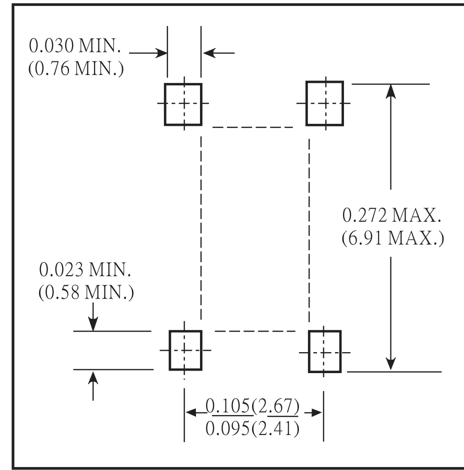
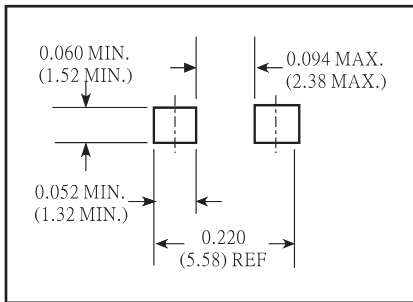


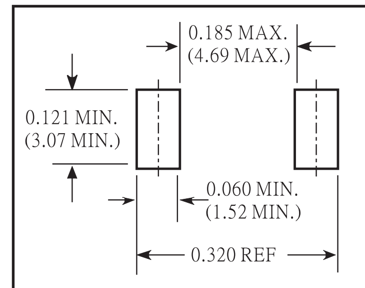
DFS



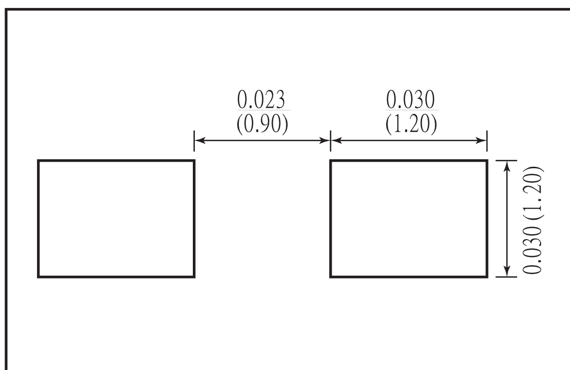
TO-269AA



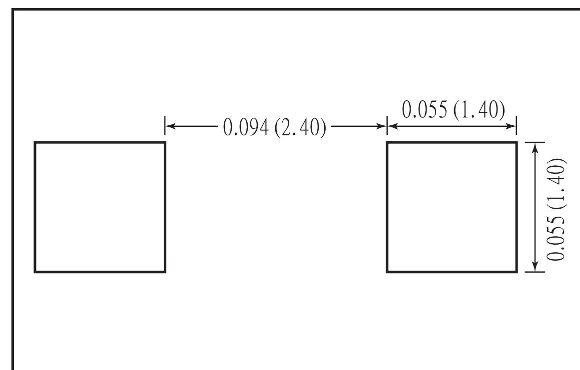
SMA / DO-214AC



SMC / DO-214AB

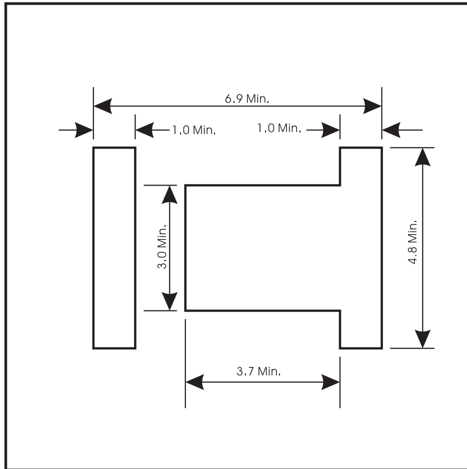


0805

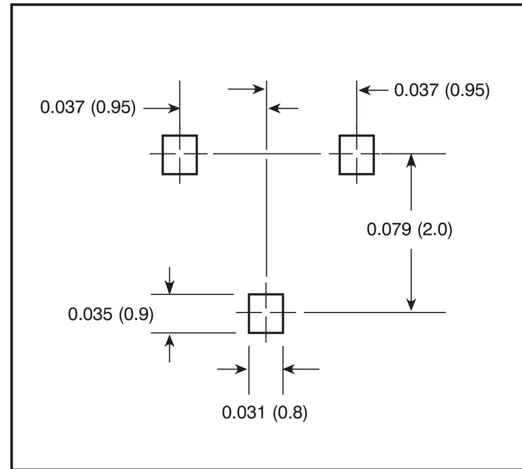


MINI-SMA / SOD-123

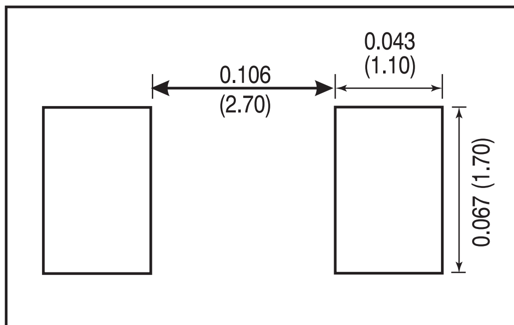
All Dimensions in inches (millimeters)



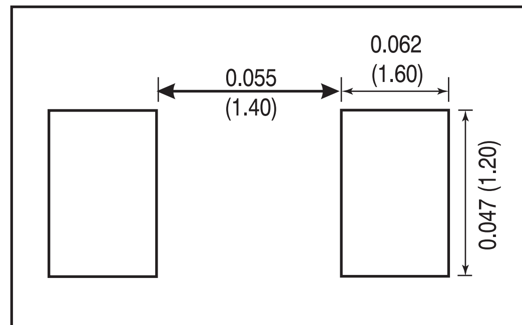
SMC-T



SOT-23

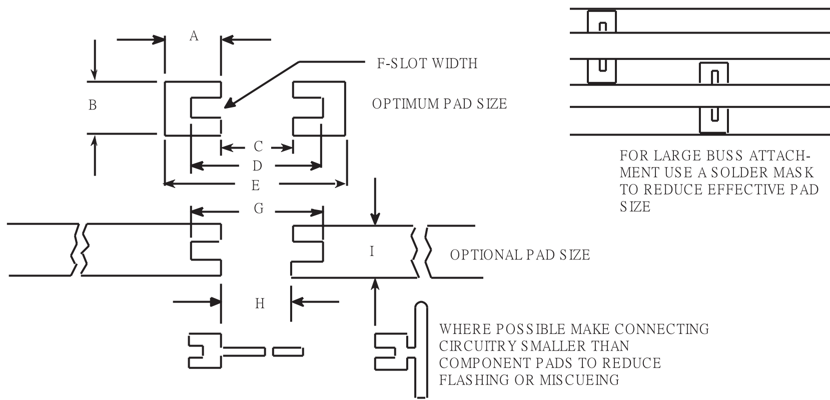


SOD-80



SOD-323

All Dimensions in inches (millimeters)



DIMENSION	GL34 D0-213AA	GL41 DO-213AB
A	.069 (1.75)	.100 (2.54)
B	.063 (1.60)	.100 (2.54)
C	.069 (1.75)	.100 (2.54)
D	.138 (3.50)	.200 (5.08)
E	.207 (5.26)	.300 (7.62)
F	.016 (.406)	.025 (.635)
G	.138 (3.50)	.200 (5.08)
H	.035 to .080 (.89 to 2.03)	.050 to .125 (1.27 to 3.17)
I	.048 (1.22) min	.075 (1.90) min

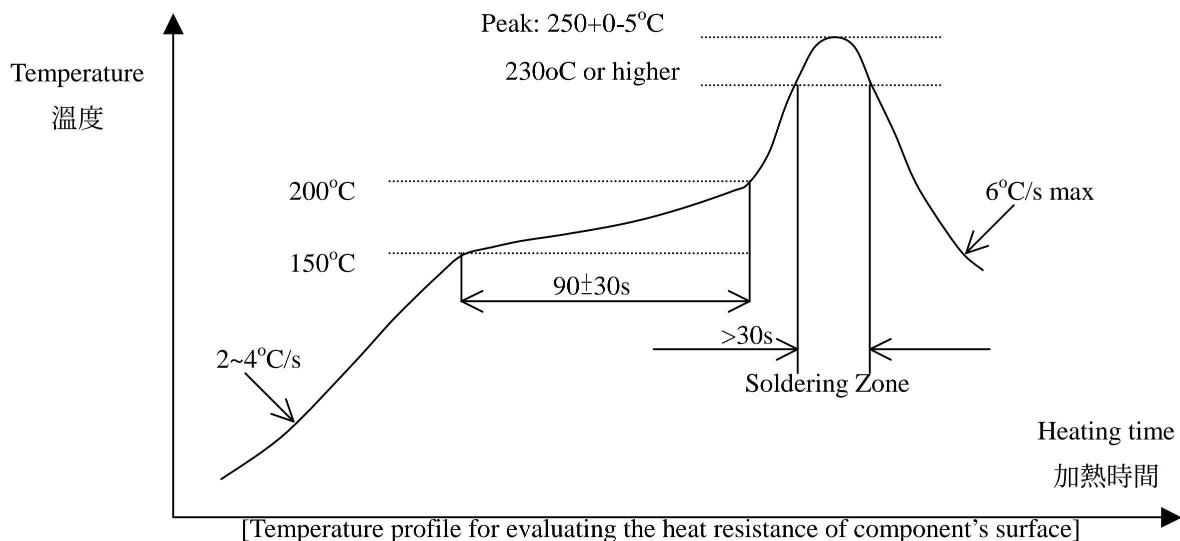
Recommended minimum soldering processing for surface mount

【Reflow condition】 Solder heat resistance test for lead-free process

Electrical and mechanical characteristics and appearance should remain the same condition after the process of

[Package opening]=>[Baking]=>[Humidification]=>[Reflow]=>[Humidication]=>[Reflow]

Reflow condition:	Peak 最高溫度	250+0/-5°C 攝氏度
	Soldering Zone 銲接區	230°C or higher ≧30sec 秒
	Pre-heating Zone 預熱區	150~200°C 90±30sec 秒



[Temperature profile for evaluating the heat resistance of component's surface]